Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			**** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2022-09-20
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	**Representative Title**	ADG Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by giovanni giacopello
Date: 2022.09.20 14:41:48 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
L9908	BAES*UR8BBAP	A	959	2022-09-20
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	140	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
Bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00710538	

Package Designator	**Package Size**	**Nbr of instances**	**Shape**	
Not Applicable	7.00x7.00x1.00	48	0	
Comment	TQFP 48 7x7x1.0 1.0 Exp Pad Down. MDF valid for CPs: L9908,L9908TR			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	**Description**
,	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	**Description**

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**true**
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.144	die - leadframe	1029

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-17 Jan 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Responsible metals sourcing	
Query	**Response**
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	**true**
The following metals are present is the component :	**Cobalt, Tantalum, Tin, Tungsten,**
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				**Response**
The Product does contain at least one of the substances listed in Chemical Control Act				**false**

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	**Response**
The product contains adhesives identified under GB 33372	**false**

Stockholm Convention Persistent Organic Pollutants	
Query	**Response**
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	**true**

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**BAES*UR8BBAP**					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	10.079	mg	supplier	die	Silicon(Si)	7440-21-3		9.452	mg	937791	67514
				supplier	metallisation	Copper(Cu)	7440-50-8		0.202	mg	20042	1443
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	99	7
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.144	mg	14287	1029
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.023	mg	2282	164
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.011	mg	1091	79
				supplier	metallisation	Tungsten(W)	7440-33-7		0.017	mg	1687	121
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.032	mg	3175	229
				supplier	passivation	Silicon oxide	7631-86-9		0.128	mg	12700	914
				supplier	polymer coating	polyimide	proprietary		0.069	mg	6846	493
Leadframe	M-004 Copper and its alloys	65.051	mg	supplier	alloy	Copper(Cu)	7440-50-8		63.392	mg	974497	452800
				supplier	alloy	Iron(Fe)	7439-89-6		1.491	mg	22920	10650
				supplier	alloy	Iron phosphide	1310-43-6		0.090	mg	1384	643
				supplier	alloy	Zinc(Zn)	7440-66-6		0.078	mg	1199	557
Die attach	M-011 Other inorganic materials	1.268	mg	supplier	glue	Silver(Ag)	7440-22-4		1.131	mg	891957	8079
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.089	mg	70189	636
				supplier	glue	Bismaleimide resin	proprietary		0.038	mg	29968	271
				supplier	glue	Epoxycyclohexylethyltrimethoxysilane	3388-04-3		0.010	mg	7886	71
Bonding wires	M-004 Copper and its alloys	0.487	mg	supplier	wire	Copper(Cu)	7440-50-8		0.487	mg	1000000	3479
Encapsulation	M-011 Other inorganic materials	61.227	mg	supplier	mold compound	Silica vitreous	60676-86-0		49.869	mg	814493	356207
				supplier	mold compound	Silicon oxide	7631-86-9		4.592	mg	75000	32800
				supplier	mold compound	Epoxy type resin	25068-38-6		4.592	mg	75000	32800
				supplier	mold compound	Phenol type resin	29690-82-2		1.837	mg	30003	13121
				supplier	mold compound	Carbon black	1333-86-4		0.337	mg	5504	2407
Connections coating	Solder	1.888	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.888	mg	1000000	13486